

ON Semiconductor			10/15/2019	
<b>Base Part</b>		<b>NHPV08S600</b>	<b>HF</b>	
<b>Orderable Part</b>		<b>NHPJ08S600G</b>	<b>Total weight (mg)</b>	<b>1938.37</b>
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
<b>Die</b>	<b>4.03</b>	Silicon (Si)	7440-21-3	100
<b>Die Attach</b>	<b>11.03</b>	Lead (Pb)	7439-92-1	95
		Tin (Sn)	7440-31-5	5
<b>Lead Frame</b>	<b>1236.66</b>	Copper (Cu)	7440-50-8	100
<b>Mold Compound-Black</b>	<b>679.88</b>	Epoxy resins	n/a	7
		Phenolic Resin	n/a	7
		Silica Amorphous (SiO2)	7631-86-9	15
		Carbon Black (C)	1333-86-4	0.5
		Fused Silica (SiO2)	60676-86-0	70.5
<b>Plating</b>	<b>6.36</b>	Tin (Sn)	7440-31-5	100
<b>Wire Bond - Al</b>	<b>0.41</b>	Aluminum (Al)	7429-90-5	100
<p><b>Materials Disclosure Disclaimer:</b> Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels of dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p><a href="http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF">http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</a></p>				